Infineon Technologies - MB90347ESPMC-GS-470E1 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	24MHz
Connectivity	CANbus, EBI/EMI, LINbus, SCI, UART/USART
Peripherals	DMA, POR, WDT
Number of I/O	82
Program Memory Size	128KB (128K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	A/D 16x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90347espmc-gs-470e1

1. Product Lineup

Part Number / Parameter	MB90V340E-101, MB90V340E-102	MB90F342E(S), MB90F342CE(S), MB90F345E(S), MB90F345CE(S), MB90F346E(S), MB90F346CE(S), MB90F347E(S), MB90F347CE(S), MB90F349E(S), MB90F349CE(S)	MB90341E(S), MB90341CE(S), MB90342E(S), MB90342CE(S), MB90346E(S), MB90346CE(S), MB90347E(S), MB90347CE(S), MB90348E(S), MB90348CE(S), MB90349E(S), MB90349CE(S)
Type	Evaluation products	Flash memory products	MASK ROM products
CPU	F^2MC-16LX CPU		
System clock	On-chip PLL clock multiplier (×1, ×2, ×3, ×4, ×6, 1/2 when PLL stops) Minimum instruction execution time : 42 ns (4 MHz osc. PLL × 6)		
ROM	External	512 Kbytes : MB90F345E(S), MB90F345CE(S) 256 Kbytes : MB90F342E(S), MB90F342CE(S), MB90F349E(S), MB90F349CE(S) 128 Kbytes : MB90F347E(S), MB90F347CE(S) 64 Kbytes : MB90F346E(S), MB90F346CE(S)	256 Kbytes : MB90342E(S), MB90342CE(S), MB90349E(S), MB90349CE(S) 128 Kbytes : MB90341E(S), MB90341CE(S), MB90347E(S), MB90347CE(S), MB90348E(S), MB90348CE(S) 64 Kbytes : MB90346E(S), MB90346CE(S)
RAM	30 Kbytes	20 Kbytes : MB90F345E(S), MB90F345CE(S) 16 Kbytes : MB90F342E(S), MB90F342CE(S), MB90F349E(S), MB90F349CE(S) 6 Kbytes : MB90F347E(S), MB90F347CE(S) 2 Kbytes : MB90F346E(S), MB90F346CE(S)	16 Kbytes : MB90341E(S), MB90341CE(S), MB90342E(S), MB90342CE(S), MB90348E(S), MB90348CE(S), MB90349E(S), MB90349CE(S) 6 Kbytes : MB90347E(S), MB90347CE(S) 2 Kbytes : MB90346E(S), MB90346CE(S)
Emulator-specific power supply*	Yes	—	
Technology	0.35 μm CMOS with regulator for built-in power supply	0.35 μm CMOS with built-in power supply regulator + Flash memory with Charge pump for programming voltage	
Operating voltage range	5 V ± 10%	3.5 V to 5.5 V : When normal operating (not using A/D converter) 4.0 V to 5.5 V : When using the A/D converter/Flash programming 4.5 V to 5.5 V : When using the external bus	
Temperature range	—	−40°C to +105°C	
Package	PGA-299	QFP-100, LQFP-100	
LIN-UART	5 channels	4 channels	
	Wide range of baud rate settings using a dedicated baud rate generator (reload timer) Special synchronous options for adapting to different synchronous serial protocols LIN functionality working either as master or slave LIN device		
I^2C (400 kbps)	2 channels	Devices with a C suffix in the part number : 2 channels Devices without a C suffix in the part number : —	

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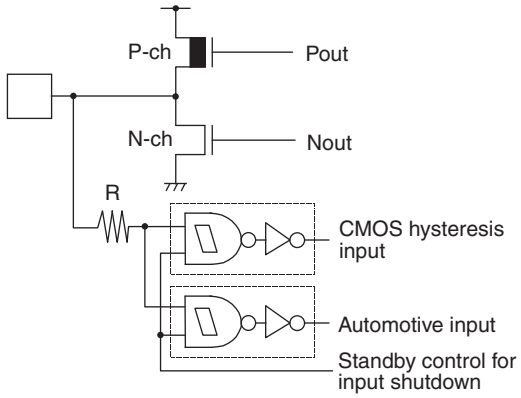
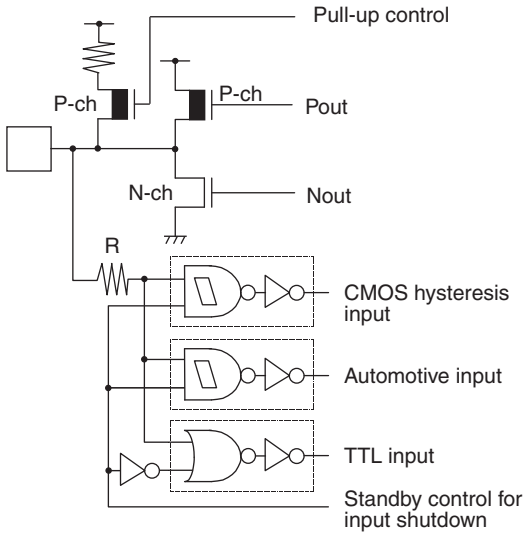
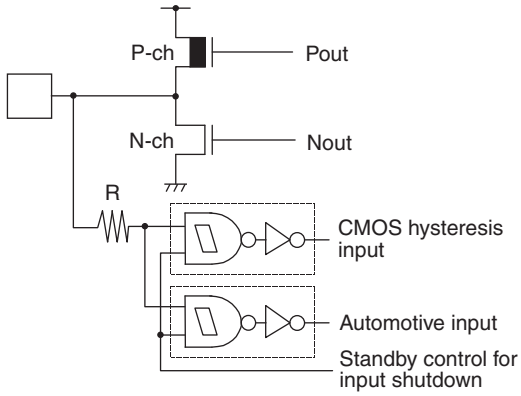
Type	Circuit	Remarks
F		■ CMOS level output (I_{OL} = 4 mA, I_{OH} = –4 mA) ■ CMOS hysteresis input (with function to disconnect input during standby) ■ Automotive input (with function to disconnect input during standby)
G		■ CMOS level output (I_{OL} = 4 mA, I_{OH} = –4 mA) ■ CMOS hysteresis input (with function to disconnect input during standby) ■ Automotive input (with function to disconnect input during standby) ■ TTL input (with function to disconnect input during standby) ■ Programmable pull-up resistor: 50 kΩ approx.
H		■ CMOS level output (I_{OL} = 3 mA, I_{OH} = –3 mA) ■ CMOS hysteresis input (with function to disconnect input during standby) ■ Automotive input (with function to disconnect input during standby)

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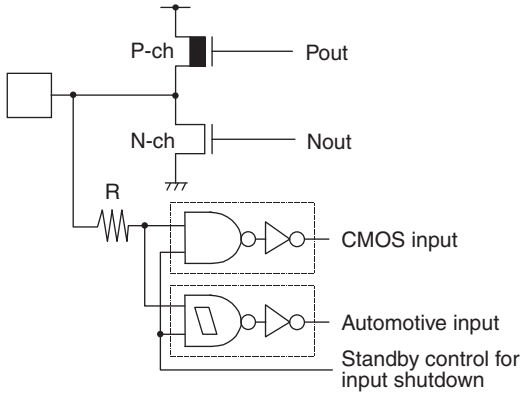
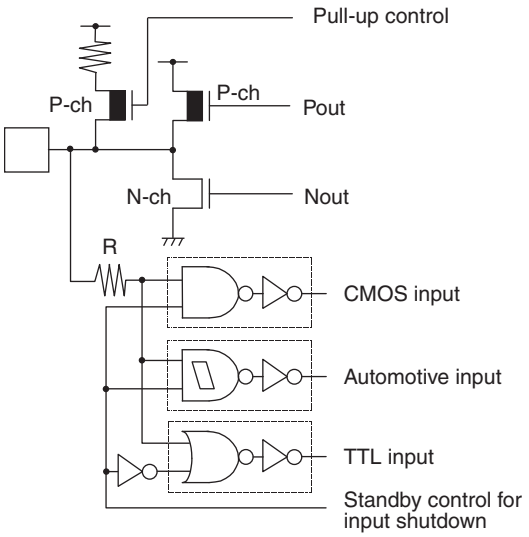
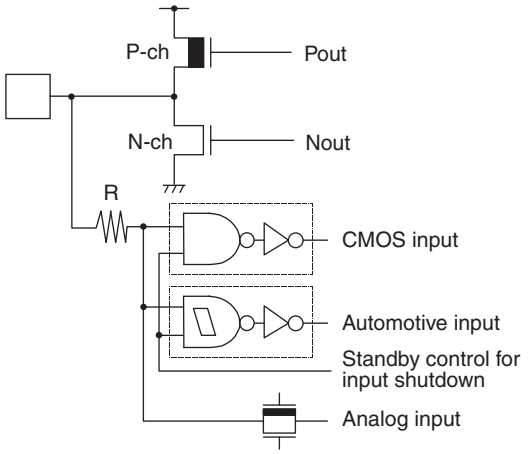
Type	Circuit	Remarks
M		■ CMOS level output (I_{OL} = 4 mA, I_{OH} = −4 mA) ■ CMOS input (with function to disconnect input during standby) ■ Automotive input (with function to disconnect input during standby)
N		■ CMOS level output (I_{OL} = 4 mA, I_{OH} = −4 mA) ■ CMOS input (with function to disconnect input during standby) ■ Automotive input (with function to disconnect input during standby) ■ TTL input (with function to disconnect input during standby) Programmable pull-up resistor: 50 kΩ approx
O		■ CMOS level output (I_{OL} = 4 mA, I_{OH} = −4 mA) ■ CMOS input (with function to disconnect input during standby) ■ Automotive input (with function to disconnect input during standby) ■ A/D converter analog input

5. Handling Devices

1. Preventing latch-up

CMOS IC may suffer latch-up under the following conditions:

- A voltage higher than V_{CC} or lower than V_{SS} is applied to an input or output pin.
- A voltage higher than the rated voltage is applied between V_{CC} and V_{SS} pins.
- The AV_{CC} power supply is applied before the V_{CC} voltage.

Latch-up may increase the power supply current drastically, causing thermal damage to the device.

For the same reason, also be careful not to let the analog power-supply voltage (AV_{CC}, AVRH) exceed the digital power-supply voltage.

2. Handling unused pins

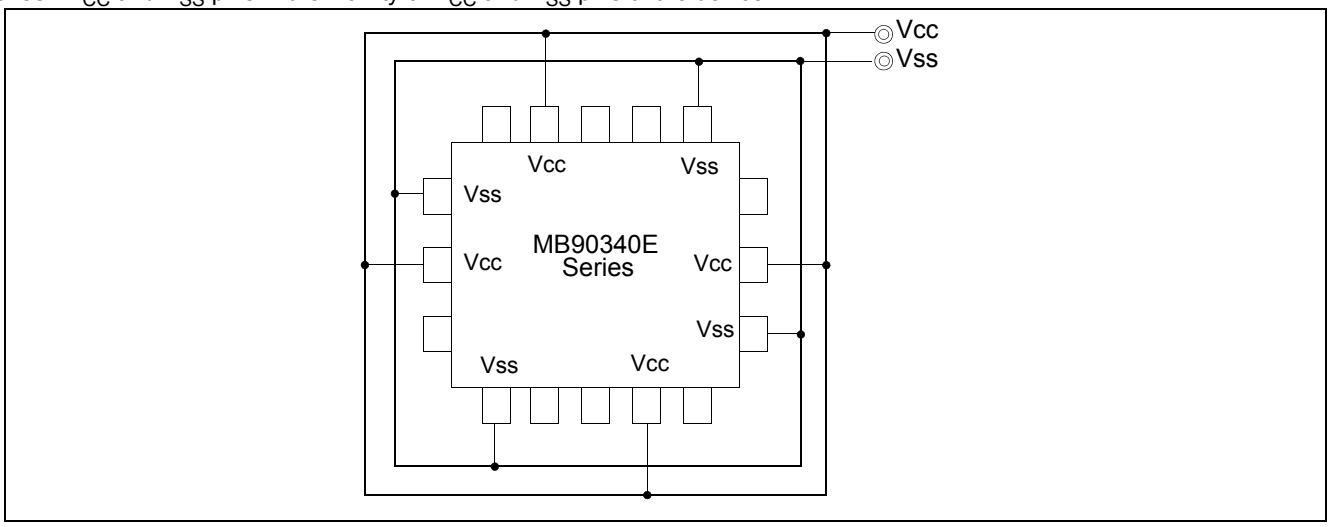
Leaving unused input terminals open may lead to permanent damage due to malfunction and latch-up; pull up or pull down the terminals through the resistors of 2 kΩ or more.

3. Power supply pins (V_{CC}/V_{SS})

- If there are multiple V_{CC} and V_{SS} pins, from the point of view of device design, pins to be of the same potential are connected inside of the device to prevent malfunction such as latch-up.

To reduce unnecessary radiation, prevent malfunctioning of the strobe signal due to the rise of ground level, and observe the standard for total output current, be sure to connect the V_{CC} and V_{SS} pins to the power supply and ground externally.
Connect V_{CC} and V_{SS} pins to the device from the current supply source at a possibly low impedance.

- As a measure against power supply noise, it is recommended to connect a capacitor of about 0.1 µF as a bypass capacitor between V_{CC} and V_{SS} pins in the vicinity of V_{CC} and V_{SS} pins of the device.



4. Mode Pins (MD0 to MD2)

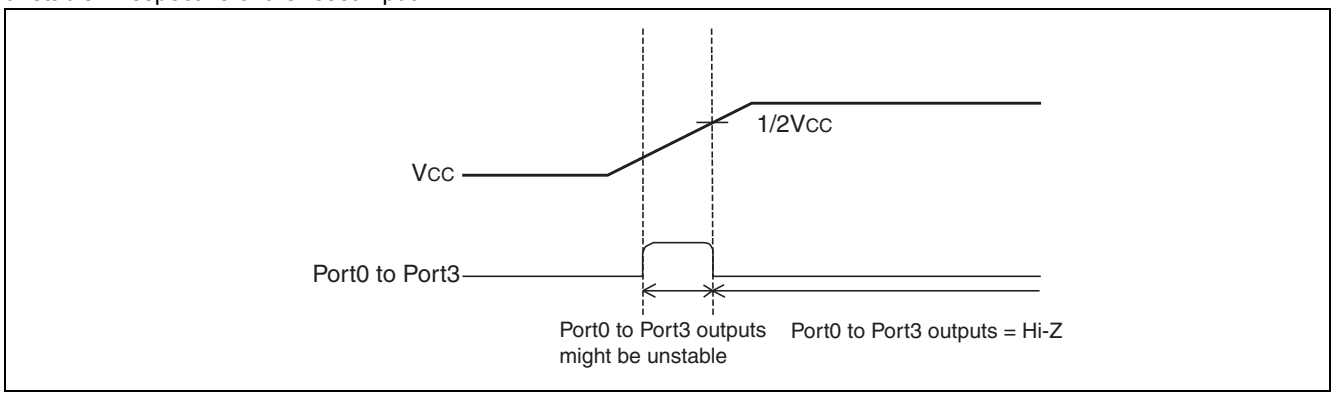
Connect the mode pins directly to V_{CC} or V_{SS} pins. To prevent the device unintentionally entering test mode due to noise, lay out the printed circuit board so as to minimize the distance from the mode pins to V_{CC} or V_{SS} pins and to provide a low-impedance connection.

13.Stabilization of power supply voltage

A sudden change in the supply voltage may cause the device to malfunction even within the V_{CC} supply voltage operating range. Therefore, the V_{CC} supply voltage should be stabilized. For reference, the supply voltage should be controlled so that V_{CC} ripple variations (peak- to-peak values) at commercial frequencies (50 MHz/60 MHz) fall below 10% of the standard V_{CC} supply voltage and the coefficient of fluctuation does not exceed 0.1 V/ms at instantaneous power switching.

14.Port 0 to Port 3 Output During Power-on (External-bus Mode)

As shown below, when the power is turned on in External-Bus mode, there is a possibility that output signal of Port 0 to Port 3 might be unstable irrespective of the reset input.



15.Notes on Using the CAN Function

To use the CAN function, please set the DIRECT bit of the CAN Direct Mode Register (CDMR) to 1.

16.Flash Security Function (except for MB90F346E)

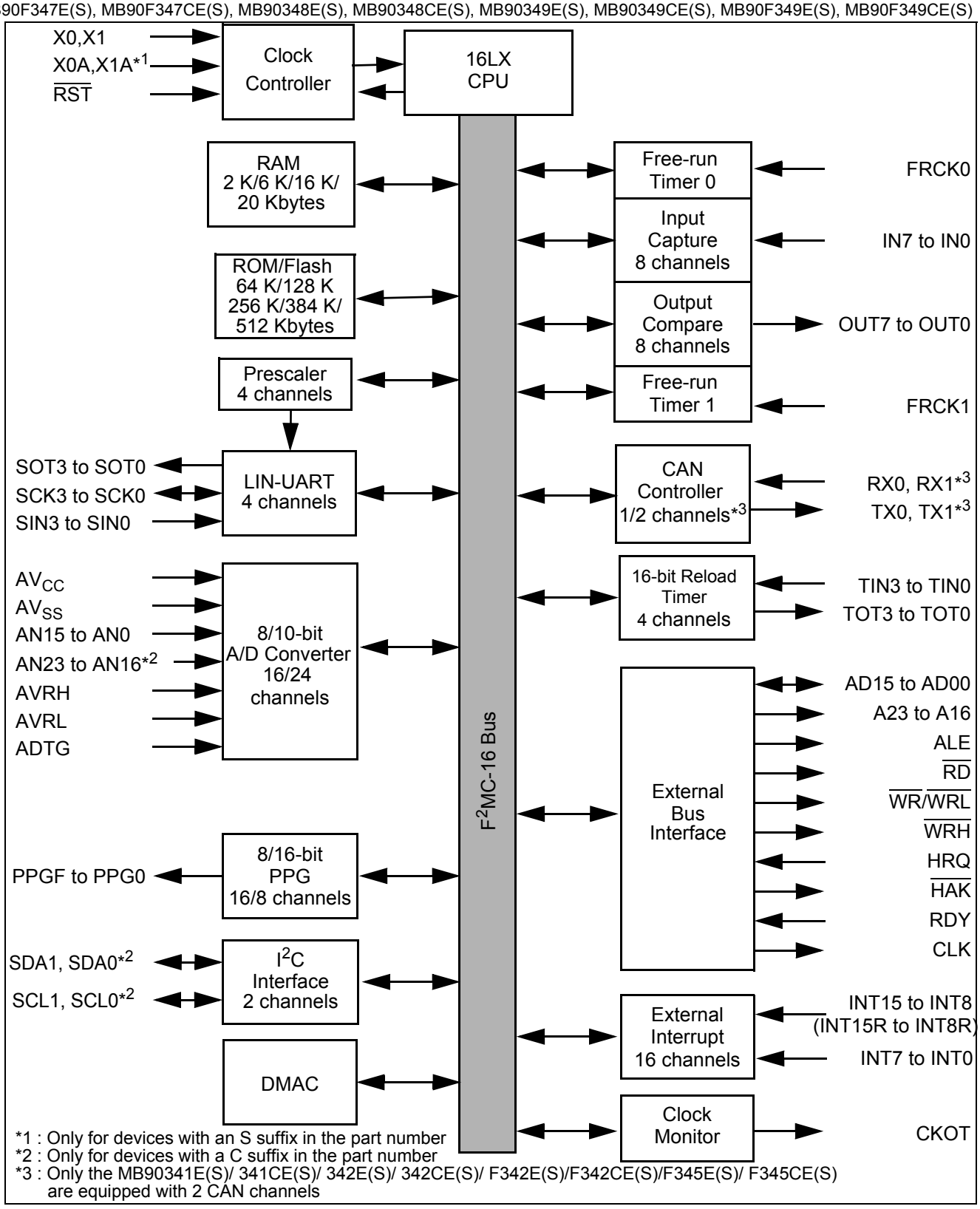
A security bit is located in the area of the flash memory.
If protection code 01_H is written in the security bit, the flash memory is in the protected state by security.
Therefore please do not write 01_H in this address if you do not use the security function.
Refer to following table for the address of the security bit.

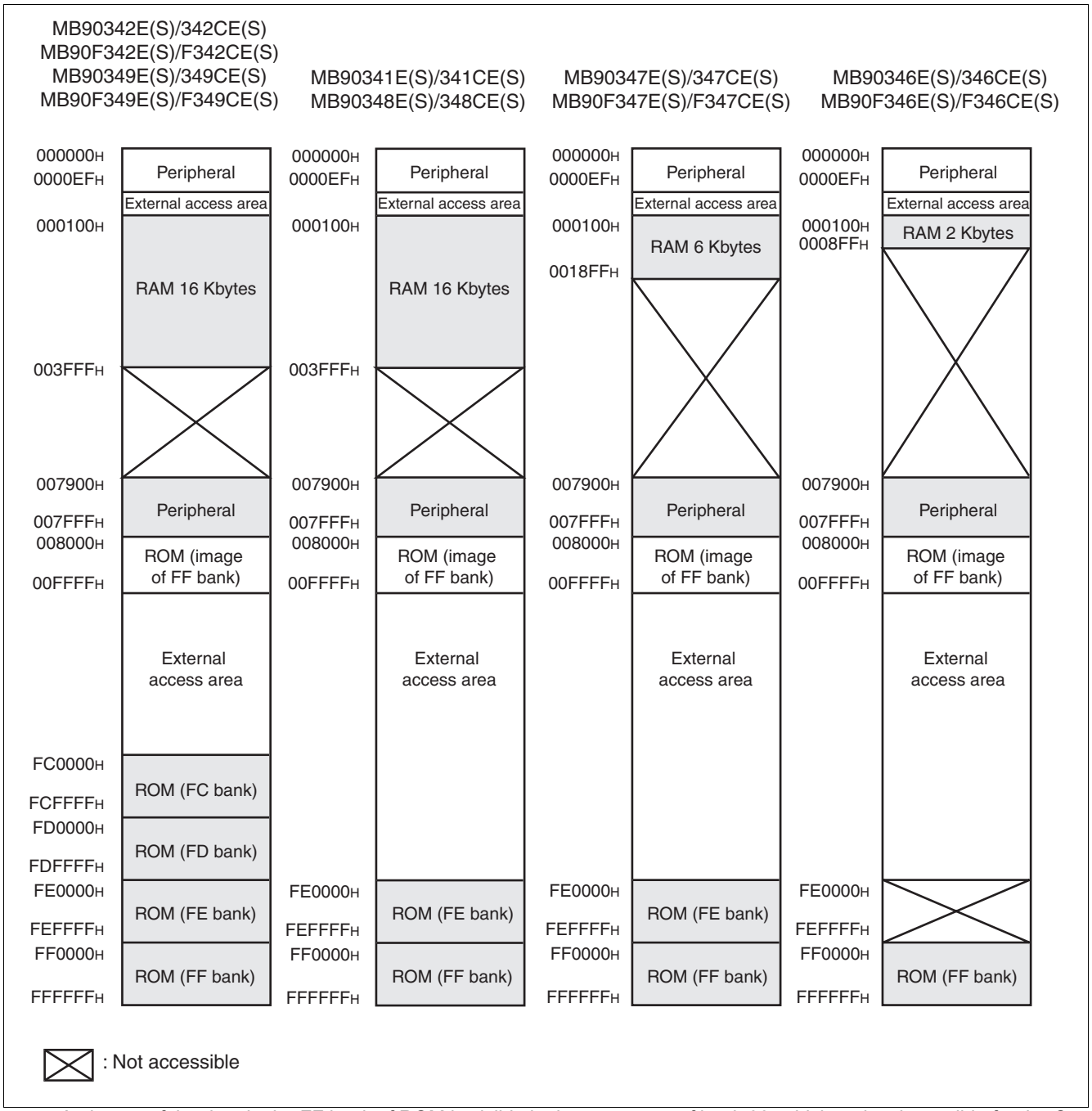
	Flash memory size	Address of the security bit
MB90F347E	Embedded 1 Mbit Flash Memory	$FE0001_H$
MB90F342E MB90F349E	Embedded 2 Mbits Flash Memory	$FC0001_H$
MB90F345E	Embedded 4 Mbits Flash Memory	$F80001_H$

17.Serial Communication

There is a possibility to receive wrong data due to the noise or other causes on the serial communication.
Therefore, design a printed circuit board so as to avoid noise.
Retransmit the data if an error occurs because of applying the checksum to the last data in consideration of receiving wrong data due to the noise.

■ MB90341E(S), MB90341CE(S), MB90342E(S), MB90342CE(S), MB90F342E(S), MB90F342CE(S), MB90F345E(S), MB90F345CE(S), MB90346E(S), MB90346CE(S), MB90F346E(S), MB90F346CE(S), MB90347E(S), MB90347CE(S), MB90F347E(S), MB90F347CE(S), MB90348E(S), MB90348CE(S), MB90349E(S), MB90349CE(S), MB90F349E(S), MB90F349CE(S)





Note: :An image of the data in the FF bank of ROM is visible in the upper part of bank 00, which makes it possible for the C compiler to use the small memory model. The lower 16 bits of addresses in the FF bank are the same as the lower 16 bits of addresses in the 00 bank so that tables stored in the ROM can be accessed without using the far specifier in the pointer declaration.
For example, when the address $00C000_H$ is accessed, the data at $FFC000_H$ in ROM is actually accessed.
The ROM area in bank FF exceeds 32 Kbytes, and its entire image cannot be shown in bank 00.
As a result, the image between $FF8000_H$ and $FFFFFF_H$ is visible in bank 00, while the image between $FF0000_H$ and $FF7FFF_H$ is visible only in bank FF.

8. I/O Map

Address	Register	Abbreviation	Access	Resource name	Initial value
000000_H	Port 0 Data Register	PDR0	R/W	Port 0	$XXXXXXXX_B$
000001_H	Port 1 Data Register	PDR1	R/W	Port 1	$XXXXXXXX_B$
000002_H	Port 2 Data Register	PDR2	R/W	Port 2	$XXXXXXXX_B$
000003_H	Port 3 Data Register	PDR3	R/W	Port 3	$XXXXXXXX_B$
000004_H	Port 4 Data Register	PDR4	R/W	Port 4	$XXXXXXXX_B$
000005_H	Port 5 Data Register	PDR5	R/W	Port 5	$XXXXXXXX_B$
000006_H	Port 6 Data Register	PDR6	R/W	Port 6	$XXXXXXXX_B$
000007_H	Port 7 Data Register	PDR7	R/W	Port 7	$XXXXXXXX_B$
000008_H	Port 8 Data Register	PDR8	R/W	Port 8	$XXXXXXXX_B$
000009_H	Port 9 Data Register	PDR9	R/W	Port 9	$XXXXXXXX_B$
$00000A_H$	Port A Data Register	PDRA	R/W	Port A	$XXXXXXXX_B$
$00000B_H$	Port 5 Analog Input Enable Register	ADER5	R/W	Port 5, A/D	11111111_B
$00000C_H$	Port 6 Analog Input Enable Register	ADER6	R/W	Port 6, A/D	11111111_B
$00000D_H$	Port 7 Analog Input Enable Register	ADER7	R/W	Port 7, A/D	11111111_B
$00000E_H$	Input Level Select Register 0	ILSR0	R/W	Ports	$XXXXXXXX_B$
$00000F_H$	Input Level Select Register 1	ILSR1	R/W	Ports	$XXXX0XXX_B$
000010_H	Port 0 Direction Register	DDR0	R/W	Port 0	00000000_B
000011_H	Port 1 Direction Register	DDR1	R/W	Port 1	00000000_B
000012_H	Port 2 Direction Register	DDR2	R/W	Port 2	00000000_B
000013_H	Port 3 Direction Register	DDR3	R/W	Port 3	00000000_B
000014_H	Port 4 Direction Register	DDR4	R/W	Port 4	00000000_B
000015_H	Port 5 Direction Register	DDR5	R/W	Port 5	00000000_B
000016_H	Port 6 Direction Register	DDR6	R/W	Port 6	00000000_B
000017_H	Port 7 Direction Register	DDR7	R/W	Port 7	00000000_B
000018_H	Port 8 Direction Register	DDR8	R/W	Port 8	00000000_B
000019_H	Port 9 Direction Register	DDR9	R/W	Port 9	00000000_B
$00001A_H$	Port A Direction Register	DDRA	R/W	Port A	00000100_B
$00001B_H$	Reserved				
$00001C_H$	Port 0 Pull-up Control Register	PUCR0	R/W	Port 0	00000000_B
$00001D_H$	Port 1 Pull-up Control Register	PUCR1	R/W	Port 1	00000000_B
$00001E_H$	Port 2 Pull-up Control Register	PUCR2	R/W	Port 2	00000000_B
$00001F_H$	Port 3 Pull-up Control Register	PUCR3	W, R/W	Port 3	00000000_B

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Address	Register	Abbreviation	Access	Resource name	Initial value
$0000A5_H$	Automatic Ready Function Select Register	ARSR	W	External Memory Access	$0011XX00_B$
$0000A6_H$	External Address Output Control Register	HACR	W		00000000_B
$0000A7_H$	Bus Control Signal Selection Register	ECSR	W		$0000000X_B$
$0000A8_H$	Watchdog Control Register	WDTC	R,W	Watchdog Timer	$XXXXX111_B$
$0000A9_H$	Time Base Timer Control Register	TBTC	W,R/W	Time Base Timer	$1XX00100_B$
$0000AA_H$	Watch Timer Control Register	WTC	R,R/W	Watch Timer	$1X001000_B$
$0000AB_H$	Reserved				
$0000AC_H$	DMA Enable L Register	DERL	R/W	DMA	00000000_B
$0000AD_H$	DMA Enable H Register	DERH	R/W		00000000_B
$0000AE_H$	Flash Control Status Register (Flash memory devices only. Otherwise reserved)	FMCS	R,R/W	Flash Memory	$000X0000_B$
$0000AF_H$	Reserved				
$0000B0_H$	Interrupt Control Register 00	ICR00	W,R/W	Interrupt Control	00000111_B
$0000B1_H$	Interrupt Control Register 01	ICR01	W,R/W		00000111_B
$0000B2_H$	Interrupt Control Register 02	ICR02	W,R/W		00000111_B
$0000B3_H$	Interrupt Control Register 03	ICR03	W,R/W		00000111_B
$0000B4_H$	Interrupt Control Register 04	ICR04	W,R/W		00000111_B
$0000B5_H$	Interrupt Control Register 05	ICR05	W,R/W		00000111_B
$0000B6_H$	Interrupt Control Register 06	ICR06	W,R/W		00000111_B
$0000B7_H$	Interrupt Control Register 07	ICR07	W,R/W		00000111_B
$0000B8_H$	Interrupt Control Register 08	ICR08	W,R/W		00000111_B
$0000B9_H$	Interrupt Control Register 09	ICR09	W,R/W		00000111_B
$0000BA_H$	Interrupt Control Register 10	ICR10	W,R/W		00000111_B
$0000BB_H$	Interrupt Control Register 11	ICR11	W,R/W		00000111_B
$0000BC_H$	Interrupt Control Register 12	ICR12	W,R/W		00000111_B
$0000BD_H$	Interrupt Control Register 13	ICR13	W,R/W		00000111_B
$0000BE_H$	Interrupt Control Register 14	ICR14	W,R/W		00000111_B
$0000BF_H$	Interrupt Control Register 15	ICR15	W,R/W		00000111_B
$0000C0_H$	D/A Converter Data 0	DAT0	R/W	D/A Converter	$XXXXXXXX_B$
$0000C1_H$	D/A Converter Data 1	DAT1	R/W		$XXXXXXXX_B$
$0000C2_H$	D/A Control 0	DACR0	R/W		$XXXXXXX0_B$
$0000C3_H$	D/A Control 1	DACR1	R/W		$XXXXXXX0_B$

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Address	Register	Abbreviation	Access	Resource name	Initial value
007948_H	Timer 0/Reload 0	TMR0/TMRLR0	R/W	16-bit Reload Timer 0	$XXXXXXXX_B$
007949_H			R/W		$XXXXXXXX_B$
$00794A_H$	Timer 1/Reload 1	TMR1/TMRLR1	R/W	16-bit Reload Timer 1	$XXXXXXXX_B$
$00794B_H$			R/W		$XXXXXXXX_B$
$00794C_H$	Timer 2/Reload 2	TMR2/TMRLR2	R/W	16-bit Reload Timer 2	$XXXXXXXX_B$
$00794D_H$			R/W		$XXXXXXXX_B$
$00794E_H$	Timer 3/Reload 3	TMR3/TMRLR3	R/W	16-bit Reload Timer 3	$XXXXXXXX_B$
$00794F_H$			R/W		$XXXXXXXX_B$
007950_H	Serial Mode Register 3	SMR3	W,R/W	UART3	00000000_B
007951_H	Serial Control Register 3	SCR3	W,R/W		00000000_B
007952_H	Reception/Transmission Data Register 3	RDR3/TDR3	R/W		00000000_B
007953_H	Serial Status Register 3	SSR3	R,R/W		00001000_B
007954_H	Extended Communication Control Register 3	ECCR3	R,W, R/W		$000000XX_B$
007955_H	Extended Status Control Register	ESCR3	R/W		00000100_B
007956_H	Baud Rate Generator Register 30	BGR30	R/W		00000000_B
007957_H	Baud Rate Generator Register 31	BGR31	R/W		00000000_B
007958_H	Serial Mode Register 4	SMR4	W,R/W	UART4	00000000_B
007959_H	Serial Control Register 4	SCR4	W,R/W		00000000_B
$00795A_H$	Reception/Transmission Data Register 4	RDR4/TDR4	R/W		00000000_B
$00795B_H$	Serial Status Register 4	SSR4	R,R/W		00001000_B
$00795C_H$	Extended Communication Control Register 4	ECCR4	R,W, R/W		$000000XX_B$
$00795D_H$	Extended Status Control Register	ESCR4	R/W		00000100_B
$00795E_H$	Baud Rate Generator Register 40	BGR40	R/W		00000000_B
$00795F_H$	Baud Rate Generator Register 41	BGR41	R/W		00000000_B
007960_H to $00796B_H$	Reserved				
$00796C_H$	Clock Output Enable Register	CLKR	R/W	Clock Monitor	$XXXX0000_B$
$00796D_H$	Reserved				
$00796E_H$	CAN Direct Mode Register	CDMR	R/W	CAN Clock sync	$XXXXXXX0_B$
$00796F_H$	CAN Switch Register	CANSWR	R/W	CAN 0/1	$XXXXXX00_B$

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11.3 DC Characteristics

($T_A = -40°C$ to $+105°C$, $V_{CC} = 5.0\ V \pm 10\%$, $f_{CP} \leq 24$ MHz, $V_{SS} = AV_{SS} = 0\ V$)

Parameter	Symbol	Pin	Condition	Value			Unit	Remarks
				Min	Typ	Max		
Input H voltage (At V_{CC} = 5 V ± 10%)	V_{IHS}	—	—	0.8 V_{CC}	—	V_{CC} + 0.3	V	Port inputs if CMOS hysteresis input levels are selected (except P12, P44, P45, P46, P47, P50, P82, P85)
	V_{IHA}	—	—	0.8 V_{CC}	—	V_{CC} + 0.3	V	Port inputs if Automotive input levels are selected
	V_{IHT}	—	—	2.0	—	V_{CC} + 0.3	V	Port inputs if TTL input levels are selected
	V_{IHS}	—	—	0.7 V_{CC}	—	V_{CC} + 0.3	V	P12, P50, P82, P85 inputs if CMOS input levels are selected
	V_{IHI}	—	—	0.7 V_{CC}	—	V_{CC} + 0.3	V	P44, P45, P46, P47 inputs if CMOS hysteresis input levels are selected
	V_{IHR}	—	—	0.8 V_{CC}	—	V_{CC} + 0.3	V	$\overline{RST}$ input pin (CMOS hysteresis)
	V_{IHM}	—	—	V_{CC} − 0.3	—	V_{CC} + 0.3	V	MD input pin
Input L voltage (At V_{CC} = 5 V ± 10%)	V_{ILS}	—	—	V_{SS} − 0.3	—	0.2 V_{CC}	V	Port inputs if CMOS hysteresis input levels are selected (except P12, P44, P45, P46, P47, P50, P82, P85)
	V_{ILA}	—	—	V_{SS} − 0.3	—	0.5 V_{CC}	V	Port inputs if Automotive input levels are selected
	V_{ILT}	—	—	V_{SS} − 0.3	—	0.8	V	Port inputs if TTL input levels are selected
	V_{ILS}	—	—	V_{SS} − 0.3	—	0.3 V_{CC}	V	P12, P50, P82, P85 inputs if CMOS input levels are selected
	V_{ILI}	—	—	V_{SS} − 0.3	—	0.3 V_{CC}	V	P44, P45, P46, P47 inputs if CMOS hysteresis input levels are selected
	V_{ILR}	—	—	V_{SS} − 0.3	—	0.2 V_{CC}	V	$\overline{RST}$ input pin (CMOS hysteresis)
	V_{ILM}	—	—	V_{SS} − 0.3	—	V_{SS} + 0.3	V	MD input pin
Output H voltage	V_{OH}	Normal outputs	V_{CC} = 4.5 V, I_{OH} = −4.0 mA	V_{CC} − 0.5	—	—	V	
Output H voltage	V_{OHI}	I^2C current outputs	V_{CC} = 4.5 V, I_{OH} = −3.0 mA	V_{CC} − 0.5	—	—	V	
Output L voltage	V_{OL}	Normal outputs	V_{CC} = 4.5 V, I_{OL} = 4.0 mA	—	—	0.4	V	
Output L voltage	V_{OLI}	I^2C current outputs	V_{CC} = 4.5 V, I_{OL} = 3.0 mA	—	—	0.4	V	

(Continued)

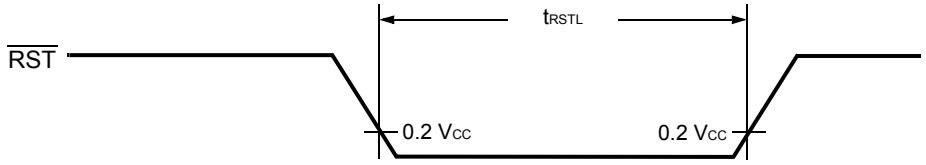
11.4.2 Reset Standby Input

(T_A = −40°C to +105°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = AV_{SS} = 0.0 V)

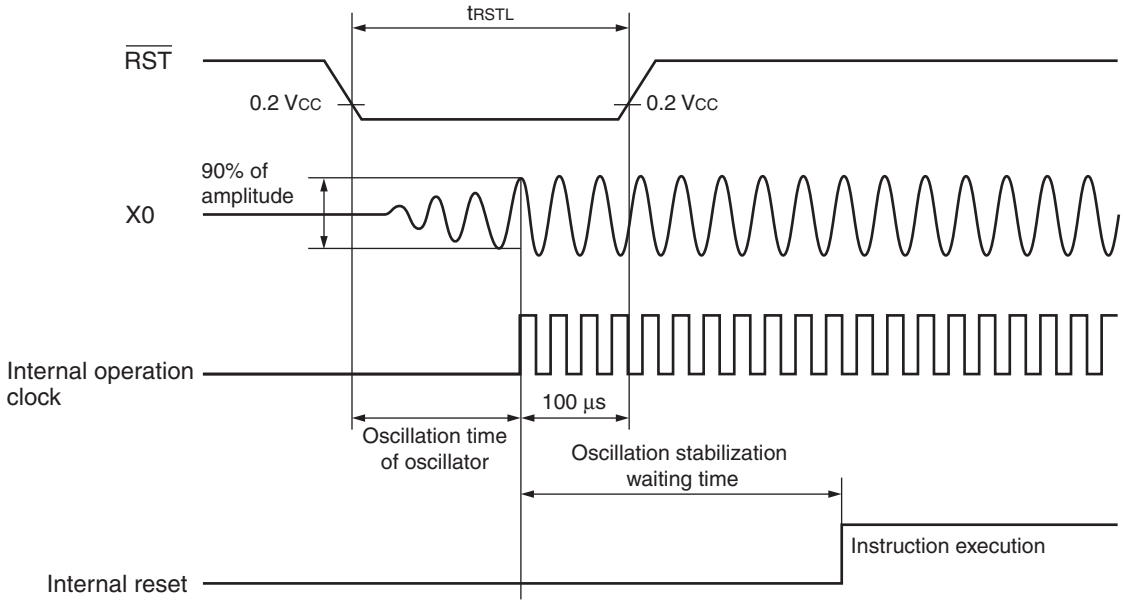
Parameter	Symbol	Pin	Value		Unit	Remarks
			Min	Max		
Reset input time	t_{RSTL}	$\overline{RST}$	500	—	ns	Under normal operation
			Oscillation time of oscillator* + 100 µs	—	µs	In Stop mode, Sub Clock mode, Sub Sleep mode and Watch mode
			100	—	µs	In Time Timer mode

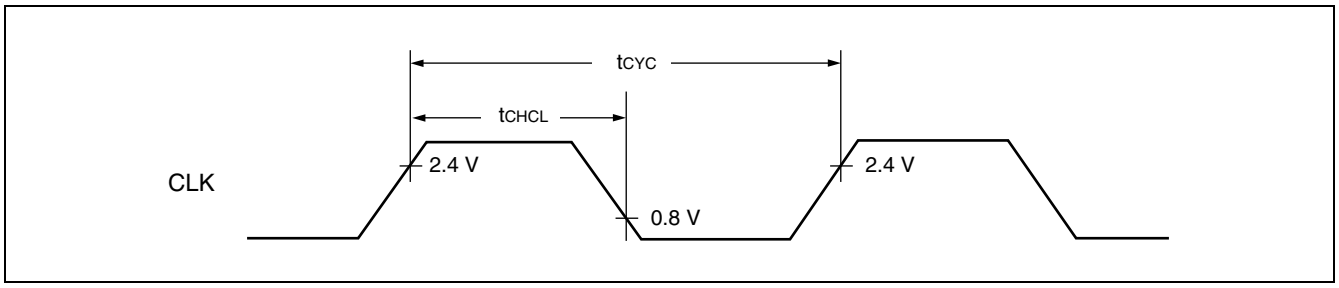
* : The oscillation time of the oscillator is the time it takes for the amplitude of the oscillations to reach 90%. For crystal oscillators, this time is between several ms and several tens of ms, for ceramic oscillators the time is between several hundred µs and several ms, and for an external clock, the time is 0 ms.

- **Under normal operation:**



- **In Stop mode, Sub Clock mode, Sub Sleep mode, Watch mode:**

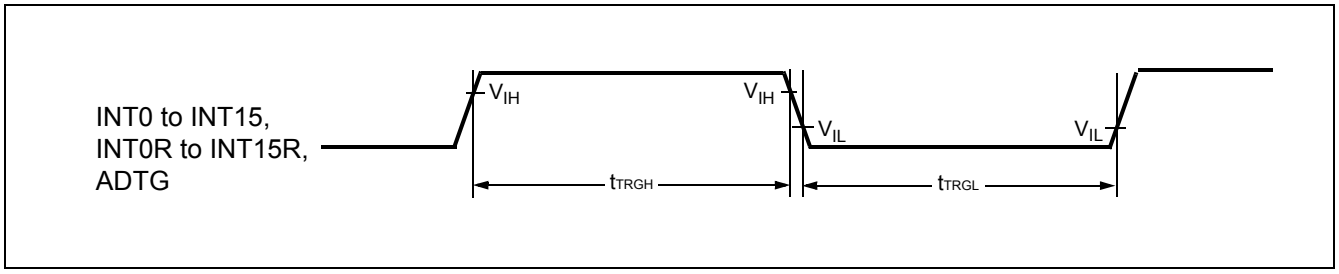



tCYC
tCHCL
CLK
2.4 V
2.4 V
0.8 V

11.4.10 Trigger Input Timing

(T_A = −40°C to +105°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = 0.0 V)

Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
Input pulse width	t_{TRGH} t_{TRGL}	INT0 to INT15, INT0R to INT15R, ADTG	—	5 t_{CP}	—	ns



11.4.13 I^2C Timing

(T_A = –40°C to +105°C, V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V)

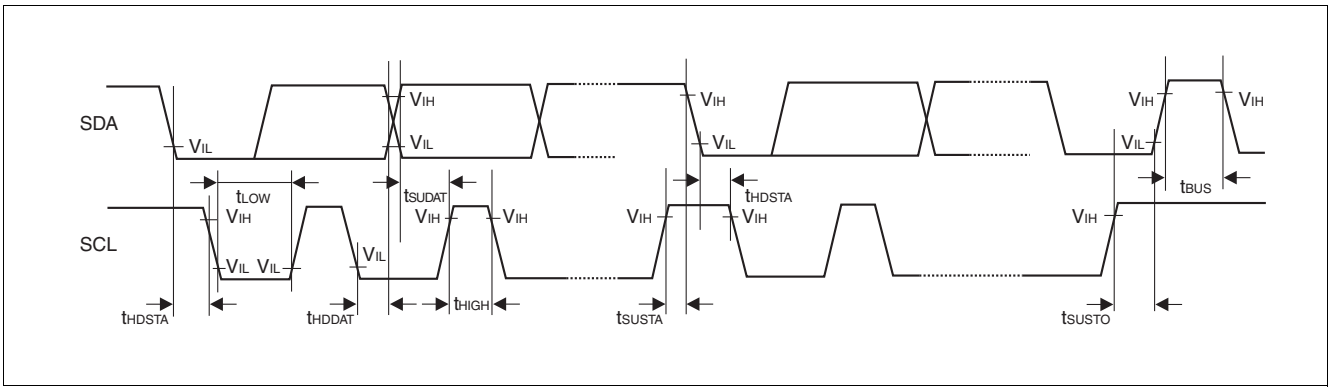
Parameter	Symbol	Condition	Standard-mode		Fast-mode*1		Unit
			Min	Max	Min	Max	
SCL clock frequency	f_{SCL}	R = 1.7 kΩ, C = 50 pF*2	0	100	0	400	kHz
Hold time (repeated) START condition SDA↓ → SCL ↓	t_{HDSTA}		4.0	—	0.6	—	µs
"L" width of the SCL clock	t_{LOW}		4.7	—	1.3	—	µs
"H" width of the SCL clock	t_{HIGH}		4.0	—	0.6	—	µs
Set-up time (repeated) START condition SCL ↑ → SDA ↓	t_{SUSTA}		4.7	—	0.6	—	µs
Data hold time SCL ↓ → SDA ↓ ↑	t_{HDDAT}		0	3.45*3	0	0.9*4	µs
Data set-up time SDA ↓ ↑ → SCL ↑	t_{SUDAT}		250	—	100	—	ns
Set-up time for STOP condition SCL ↑ → SDA ↑	t_{SUSTO}		4.0	—	0.6	—	µs
Bus free time between a STOP and START condition	t_{BUS}		4.7	—	1.3	—	µs

*1:For use at over 100 kHz, set the machine clock to at least 6 MHz.

*2:R,C: Pull-up resistor and load capacitor of the SCL and SDA lines.

*3:The maximum t_{HDDAT} meets the requirement that it does not extend the "L" width (t_{LOW}) of the SCL signal.

*4:A Fast-mode I^2C-bus device can be used in a Standard-mode I^2C-bus system, but the requirement $t_{SUDAT} \geq 250$ ns must then be met.



11.8 Flash Memory Program/Erase Characteristics

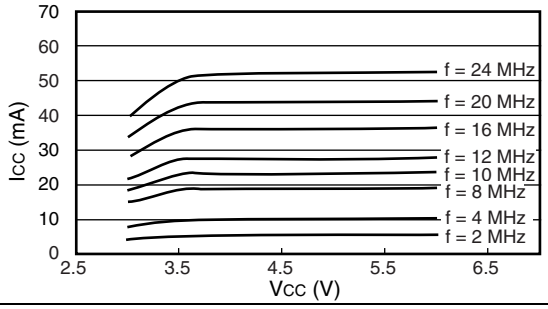
Parameter	Conditions	Value			Unit	Remarks
		Min	Typ	Max		
Sector erase time	$T_A = +25°C$ $V_{CC} = 5.0$ V	—	1	15	s	Excludes programming prior to erasure
Chip erase time		—	9	—	s	Excludes programming prior to erasure
Word (16-bit width) programming time		—	16	3600	µs	Except for the over head time of the system
Program/Erase cycle	—	10000	—	—	cycle	
Flash Data Retention Time	Average $T_A = +85°C$	20	—	—	year	*

* : This value was converted from the results of evaluating the reliability of the technology (using Arrhenius equation to translate high temperature measurements into normalized value at +85°C) .

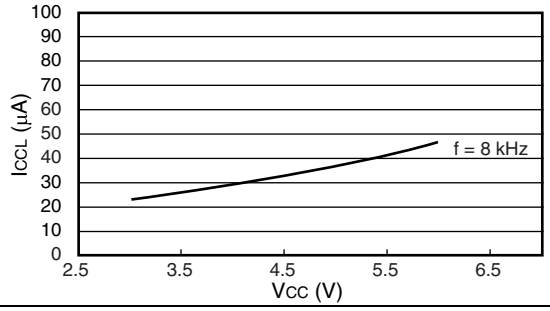
12. Example Characteristics

- MB90F346E, MB90F346ES, MB90F346CE, MB90F346CES

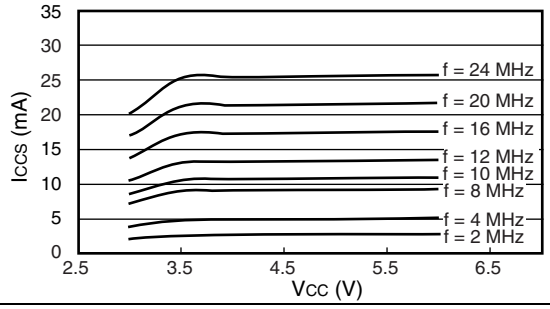
$I_{CC} - V_{CC}$
$T_A = +25°C$, external clock operation, f = Internal operation frequency



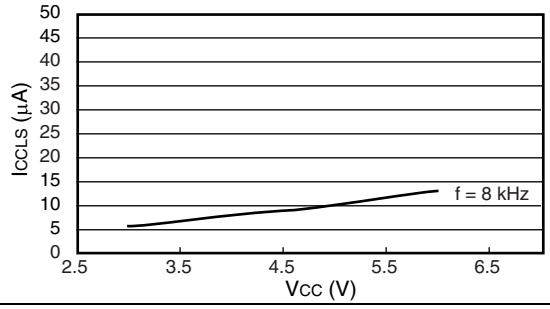
$I_{CCL} - V_{CC}$
$T_A = +25°C$, external clock operation, f = Internal operation frequency



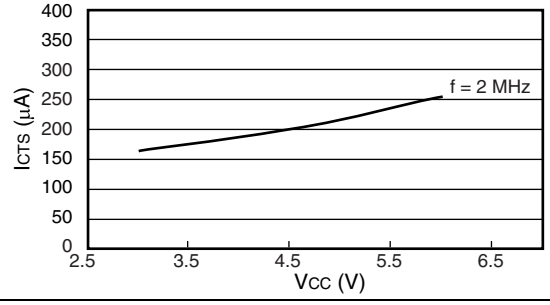
$I_{CCS} - V_{CC}$
$T_A = +25°C$, external clock operation, f = Internal operation frequency



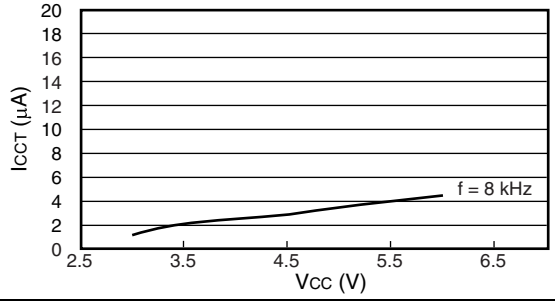
$I_{CCLS} - V_{CC}$
$T_A = +25°C$, external clock operation, f = Internal operation frequency



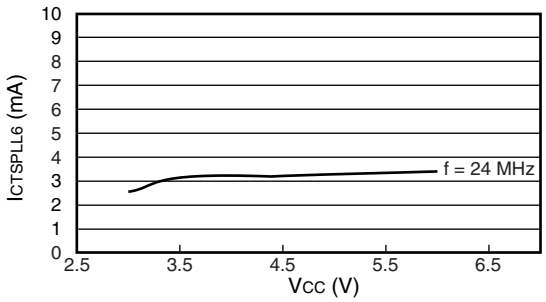
$I_{CTS} - V_{CC}$
$T_A = +25°C$, external clock operation, f = Internal operation frequency



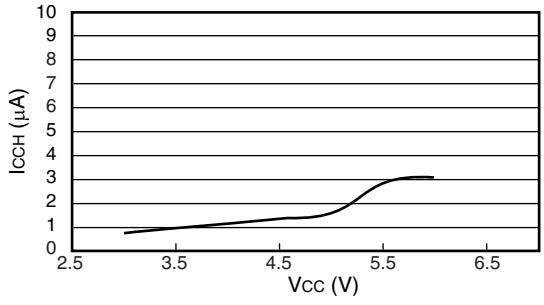
$I_{CCT} - V_{CC}$
$T_A = +25°C$, external clock operation, f = Internal operation frequency



$I_{CTSPLL6} - V_{CC}$
$T_A = +25°C$, external clock operation, f = Internal operation frequency

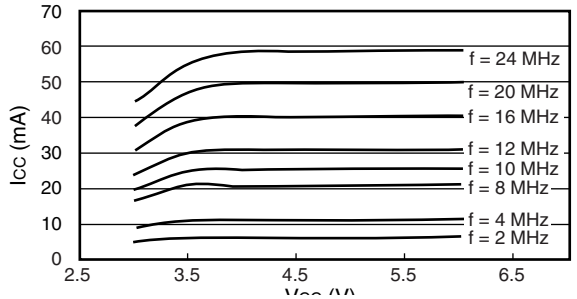


$I_{CCH} - V_{CC}$
$T_A = +25°C$, stopped

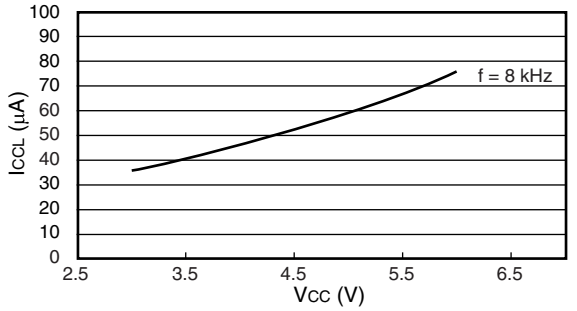


■ MB90F345E, MB90F345ES, MB90F345CE, MB90F345CES

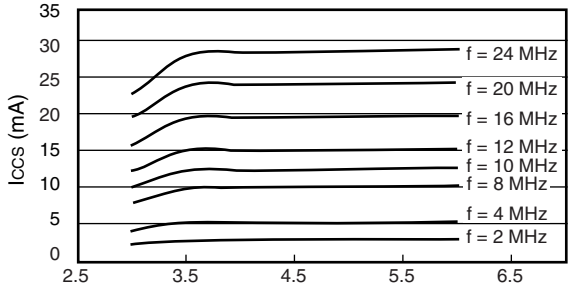
$I_{CC} - V_{CC}$
$T_A = +25°C$, external clock operation f = Internal operation frequency



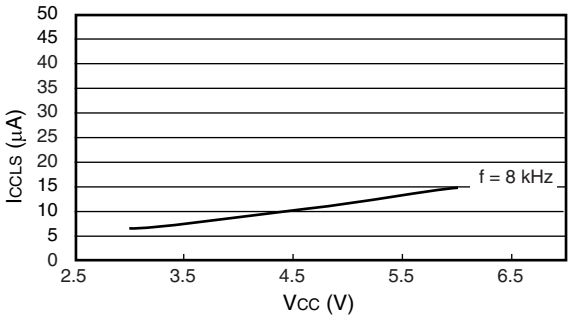
$I_{CCL} - V_{CC}$
$T_A = +25°C$, external clock operation f = Internal operation frequency



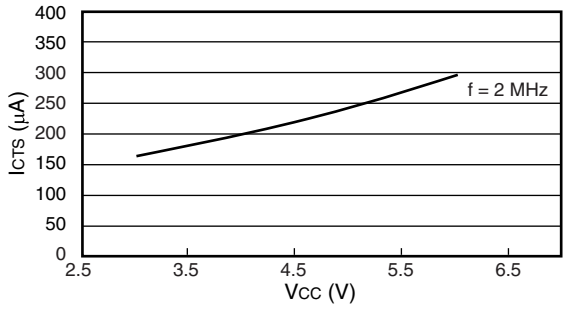
$I_{CCS} - V_{CC}$
$T_A = +25°C$, external clock operation f = Internal operation frequency



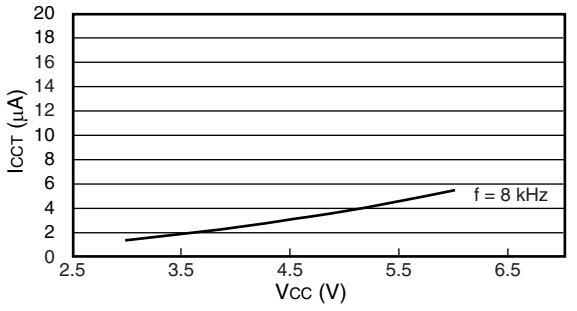
$I_{CCLS} - V_{CC}$
$T_A = +25°C$, external clock operation f = Internal operation frequency



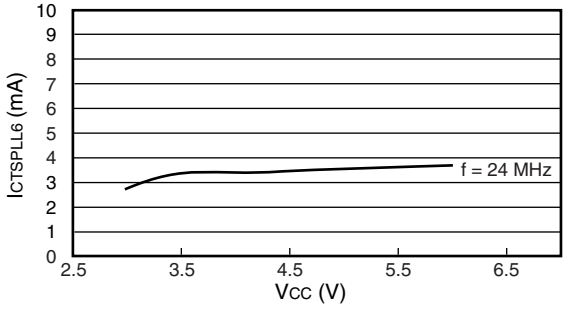
$I_{CTS} - V_{CC}$
$T_A = +25°C$, external clock operation f = Internal operation frequency



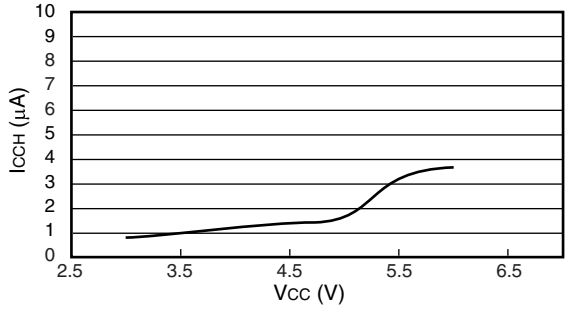
$I_{CCT} - V_{CC}$
$T_A = +25°C$, external clock operation f = Internal operation frequency



$I_{CTSPLL6} - V_{CC}$
$T_A = +25°C$, external clock operation f = Internal operation frequency



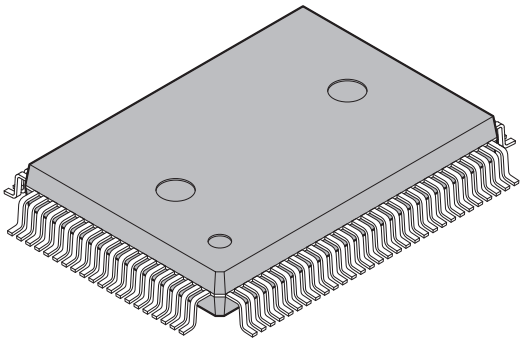
$I_{CCH} - V_{CC}$
$T_A = +25°C$, stopped



(Continued)

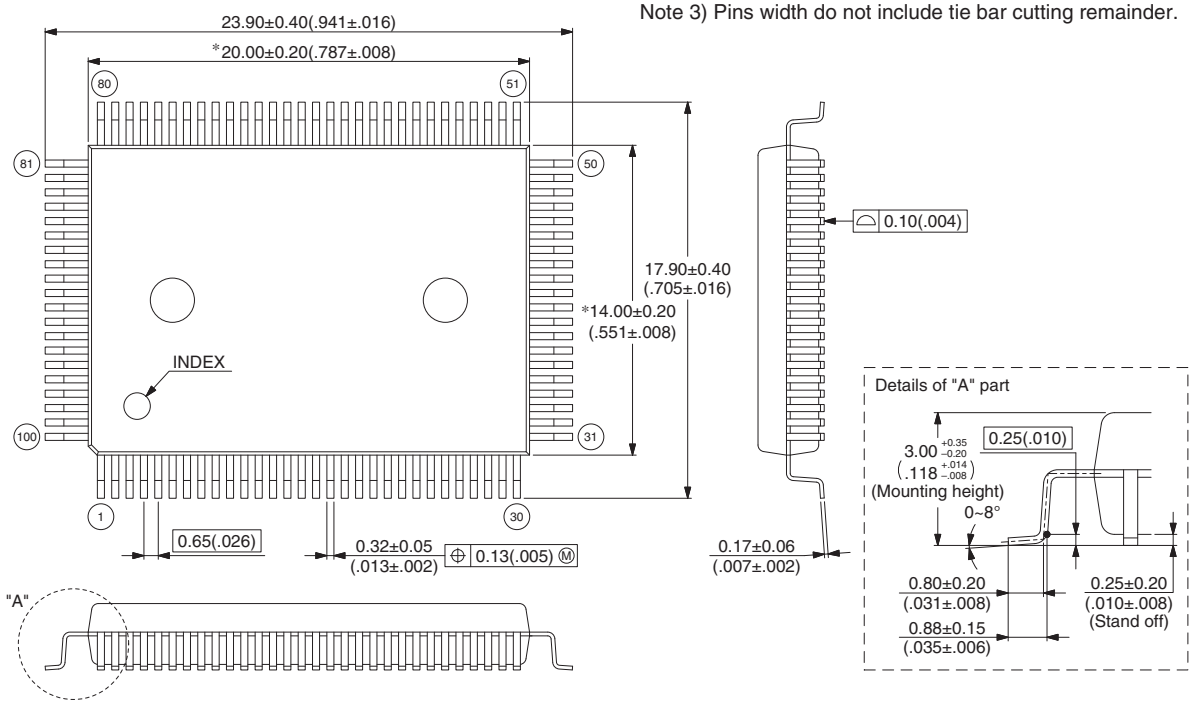
Part number	Package	Remarks
MB90346EPF	100-pin plastic QFP (FPT-100P-M06)	
MB90346ESPF		
MB90346CEPF		
MB90346CESPF		
MB90346EPMC	100-pin plastic LQFP (FPT-100P-M20)	
MB90346ESPMC		
MB90346CEPMC		
MB90346CESPMC		
MB90347EPF	100-pin plastic QFP (FPT-100P-M06)	
MB90347ESPF		
MB90347CEPF		
MB90347CESPF		
MB90347EPMC	100-pin plastic LQFP (FPT-100P-M20)	
MB90347ESPMC		
MB90347CEPMC		
MB90347CESPMC		
MB90348EPF	100-pin plastic QFP (FPT-100P-M06)	
MB90348ESPF		
MB90348CEPF		
MB90348CESPF		
MB90348EPMC	100-pin plastic LQFP (FPT-100P-M20)	
MB90348ESPMC		
MB90348CEPMC		
MB90348CESPMC		
MB90349EPF	100-pin plastic QFP (FPT-100P-M06)	
MB90349ESPF		
MB90349CEPF		
MB90349CESPF		
MB90349EPMC	100-pin plastic LQFP (FPT-100P-M20)	
MB90349ESPMC		
MB90349CEPMC		
MB90349CESPMC		
MB90V340E-101CR	299-pin ceramic PGA (PGA-299C-A01)	For evaluation
MB90V340E-102CR		

(Continued)

100-pin plastic QFP		
	Lead pitch	0.65 mm
	Package width × package length	14.00 × 20.00 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	3.35 mm MAX
	Code (Reference)	P-QFP100-14×20-0.65
(FPT-100P-M06)		

100-pin plastic QFP
(FPT-100P-M06)

Note 1) * : These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches).
Note: The values in parentheses are reference values.